



Welcome to [E-XFL.COM](https://www.e-xfl.com)

### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	H8/300H
Core Size	16-Bit
Speed	20MHz
Connectivity	SCI
Peripherals	PWM, WDT
Number of I/O	30
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 75°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (10x10)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/renesas-electronics-america/df36024fxv">https://www.e-xfl.com/product-detail/renesas-electronics-america/df36024fxv</a>

## Notice

1. All information included in this document is current as of the date this document is issued. Such information, however, is subject to change without any prior notice. Before purchasing or using any Renesas Electronics products listed herein, please confirm the latest product information with a Renesas Electronics sales office. Also, please pay regular and careful attention to additional and different information to be disclosed by Renesas Electronics such as that disclosed through our website.
2. Renesas Electronics does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Renesas Electronics products or technical information described in this document. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
3. You should not alter, modify, copy, or otherwise misappropriate any Renesas Electronics product, whether in whole or in part.
4. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation of these circuits, software, and information in the design of your equipment. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from the use of these circuits, software, or information.
5. When exporting the products or technology described in this document, you should comply with the applicable export control laws and regulations and follow the procedures required by such laws and regulations. You should not use Renesas Electronics products or the technology described in this document for any purpose relating to military applications or use by the military, including but not limited to the development of weapons of mass destruction. Renesas Electronics products and technology may not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations.
6. Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.
7. Renesas Electronics products are classified according to the following three quality grades: "Standard", "High Quality", and "Specific". The recommended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below. You must check the quality grade of each Renesas Electronics product before using it in a particular application. You may not use any Renesas Electronics product for any application categorized as "Specific" without the prior written consent of Renesas Electronics. Further, you may not use any Renesas Electronics product for any application for which it is not intended without the prior written consent of Renesas Electronics. Renesas Electronics shall not be in any way liable for any damages or losses incurred by you or third parties arising from the use of any Renesas Electronics product for an application categorized as "Specific" or for which the product is not intended where you have failed to obtain the prior written consent of Renesas Electronics. The quality grade of each Renesas Electronics product is "Standard" unless otherwise expressly specified in a Renesas Electronics data sheets or data books, etc.

"Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; and industrial robots.

"High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control systems; anti-disaster systems; anti-crime systems; safety equipment; and medical equipment not specifically designed for life support.

"Specific": Aircraft; aerospace equipment; submersible repeaters; nuclear reactor control systems; medical equipment or systems for life support (e.g. artificial life support devices or systems), surgical implantations, or healthcare intervention (e.g. excision, etc.), and any other applications or purposes that pose a direct threat to human life.
8. You should use the Renesas Electronics products described in this document within the range specified by Renesas Electronics, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas Electronics shall have no liability for malfunctions or damages arising out of the use of Renesas Electronics products beyond such specified ranges.
9. Although Renesas Electronics endeavors to improve the quality and reliability of its products, semiconductor products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Further, Renesas Electronics products are not subject to radiation resistance design. Please be sure to implement safety measures to guard them against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas Electronics product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or system manufactured by you.
10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. Please use Renesas Electronics products in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Renesas Electronics assumes no liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
11. This document may not be reproduced or duplicated, in any form, in whole or in part, without prior written consent of Renesas Electronics.
12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products, or if you have any other inquiries.

(Note 1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its majority-owned subsidiaries.

(Note 2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

Figure 5.5 Typical Connection to Ceramic Resonator.....	66
Figure 5.6 Example of External Clock Input.....	67
Figure 5.7 Example of Incorrect Board Design.....	68

## Section 6 Power-Down Modes

Figure 6.1 Mode Transition Diagram .....	73
--	----

## Section 7 ROM

Figure 7.1 Flash Memory Block Configuration.....	78
Figure 7.2 Programming/Erasing Flowchart Example in User Program Mode.....	85
Figure 7.3 Program/Program-Verify Flowchart .....	87
Figure 7.4 Erase/Erase-Verify Flowchart .....	90

## Section 9 I/O Ports

Figure 9.1 Port 1 Pin Configuration.....	95
Figure 9.2 Port 2 Pin Configuration.....	100
Figure 9.3 Port 5 Pin Configuration.....	102
Figure 9.4 Port 7 Pin Configuration.....	108
Figure 9.5 Port 8 Pin Configuration.....	112
Figure 9.6 Port B Pin Configuration.....	115

## Section 10 Timer V

Figure 10.1 Block Diagram of Timer V .....	118
Figure 10.2 Increment Timing with Internal Clock .....	127
Figure 10.3 Increment Timing with External Clock.....	127
Figure 10.4 OVF Set Timing .....	127
Figure 10.5 CMFA and CMFB Set Timing .....	128
Figure 10.6 TMOV Output Timing .....	128
Figure 10.7 Clear Timing by Compare Match.....	128
Figure 10.8 Clear Timing by TMRIV Input .....	129
Figure 10.9 Pulse Output Example.....	130
Figure 10.10 Example of Pulse Output Synchronized to TRGV Input.....	131
Figure 10.11 Contention between TCNTV Write and Clear .....	132
Figure 10.12 Contention between TCORA Write and Compare Match.....	133
Figure 10.13 Internal Clock Switching and TCNTV Operation.....	133

## Section 11 Timer W

Figure 11.1 Timer W Block Diagram.....	137
Figure 11.2 Free-Running Counter Operation.....	148
Figure 11.3 Periodic Counter Operation.....	149
Figure 11.4 0 and 1 Output Example (TOA = 0, TOB = 1).....	149
Figure 11.5 Toggle Output Example (TOA = 0, TOB = 1) .....	150
Figure 11.6 Toggle Output Example (TOA = 0, TOB = 1) .....	150



Symbol	Description
:3/:8/:16/:24	3-, 8-, 16-, or 24-bit length

Note: \* General registers include 8-bit registers (R0H to R7H, R0L to R7L), 16-bit registers (R0 to R7, E0 to E7), and 32-bit registers/address registers (ER0 to ER7).

**Table 2.2 Data Transfer Instructions**

Instruction	Size*	Function
MOV	B/W/L	(EAs) → Rd, Rs → (EAd) Moves data between two general registers or between a general register and memory, or moves immediate data to a general register.
MOVFP	B	(EAs) → Rd, Cannot be used in this LSI.
MOVTPE	B	Rs → (EAs) Cannot be used in this LSI.
POP	W/L	@SP+ → Rn Pops a general register from the stack. POP.W Rn is identical to MOV.W @SP+, Rn. POP.L ERn is identical to MOV.L @SP+, ERn.
PUSH	W/L	Rn → @-SP Pushes a general register onto the stack. PUSH.W Rn is identical to MOV.W Rn, @-SP. PUSH.L ERn is identical to MOV.L ERn, @-SP.

Note: \* Refers to the operand size.

B: Byte

W: Word

L: Longword

## 7.5 Program/Erase Protection

There are three kinds of flash memory program/erase protection; hardware protection, software protection, and error protection.

### 7.5.1 Hardware Protection

Hardware protection refers to a state in which programming/erasing of flash memory is forcibly disabled or aborted because of a transition to reset, subsleep mode or standby mode. Flash memory control register 1 (FLMCR1), flash memory control register 2 (FLMCR2), and erase block register 1 (EBR1) are initialized. In a reset via the  $\overline{\text{RES}}$  pin, the reset state is not entered unless the  $\overline{\text{RES}}$  pin is held low until oscillation stabilizes after powering on. In the case of a reset during operation, hold the  $\overline{\text{RES}}$  pin low for the  $\overline{\text{RES}}$  pulse width specified in the AC Characteristics section.

### 7.5.2 Software Protection

Software protection can be implemented against programming/erasing of all flash memory blocks by clearing the SWE bit in FLMCR1. When software protection is in effect, setting the P or E bit in FLMCR1 does not cause a transition to program mode or erase mode. By setting the erase block register 1 (EBR1), erase protection can be set for individual blocks. When EBR1 is set to H'00, erase protection is set for all blocks.

### 7.5.3 Error Protection

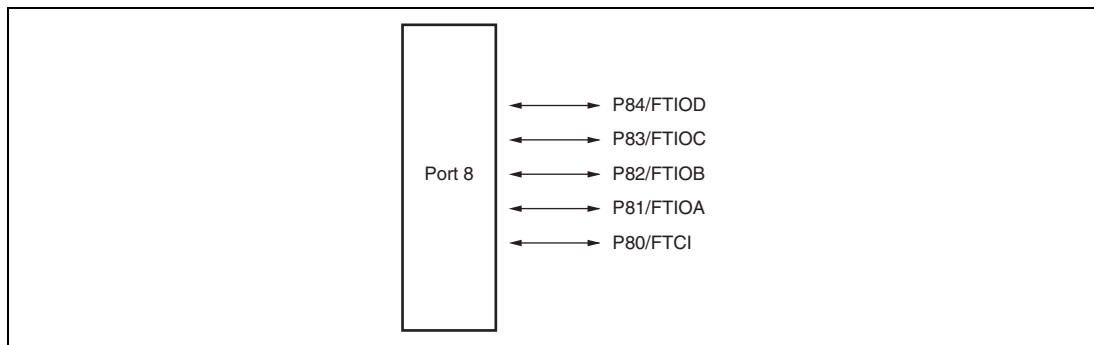
In error protection, an error is detected when CPU runaway occurs during flash memory programming/erasing, or operation is not performed in accordance with the program/erase algorithm, and the program/erase operation is aborted. Aborting the program/erase operation prevents damage to the flash memory due to overprogramming or overerasing.

When the following errors are detected during programming/erasing of flash memory, the FLER bit in FLMCR2 is set to 1, and the error protection state is entered.

- When the flash memory of the relevant address area is read during programming/erasing (including vector read and instruction fetch)
- Immediately after exception handling excluding a reset during programming/erasing
- When a SLEEP instruction is executed during programming/erasing

## 9.5 Port 8

Port 8 is a general I/O port also functioning as a timer W I/O pin. Each pin of the port 8 is shown in figure 9.5. The register setting of the timer W has priority for functions of the pins P84/FTIOD, P83/FTIOC, P82/FTIOB, and P81/FTIOA. The P80/FTCI pin also functions as a timer W input port that is connected to the timer W regardless of the register setting of port 8.



**Figure 9.5 Port 8 Pin Configuration**

Port 8 has the following registers.

- Port control register 8 (PCR8)
- Port data register 8 (PDR8)

### 9.5.1 Port Control Register 8 (PCR8)

PCR8 selects inputs/outputs in bit units for pins to be used as general I/O ports of port 8.

Bit	Bit Name	Initial Value	R/W	Description
7 to 5	—	—	—	Reserved
4	PCR84	0	W	When each of the port 8 pins P84 to P80 functions as a general I/O port, setting a PCR8 bit to 1 makes the corresponding pin an output port, while clearing the bit to 0 makes the pin an input port.
3	PCR83	0	W	
2	PCR82	0	W	
1	PCR81	0	W	
0	PCR80	0	W	

## 11.2 Input/Output Pins

Table 11.2 summarizes the timer W pins.

**Table 11.2 Pin Configuration**

Name	Abbreviation	Input/Output	Function
External clock input	FTCI	Input	External clock input pin
Input capture/output compare A	FTIOA	Input/output	Output pin for GRA output compare or input pin for GRA input capture
Input capture/output compare B	FTIOB	Input/output	Output pin for GRB output compare, input pin for GRB input capture, or PWM output pin in PWM mode
Input capture/output compare C	FTIOC	Input/output	Output pin for GRC output compare, input pin for GRC input capture, or PWM output pin in PWM mode
Input capture/output compare D	FTIOD	Input/output	Output pin for GRD output compare, input pin for GRD input capture, or PWM output pin in PWM mode

## 11.3 Register Descriptions

The timer W has the following registers.

- Timer mode register W (TMRW)
- Timer control register W (TCRW)
- Timer interrupt enable register W (TIERW)
- Timer status register W (TSRW)
- Timer I/O control register 0 (TIOR0)
- Timer I/O control register 1 (TIOR1)
- Timer counter (TCNT)
- General register A (GRA)
- General register B (GRB)
- General register C (GRC)
- General register D (GRD)



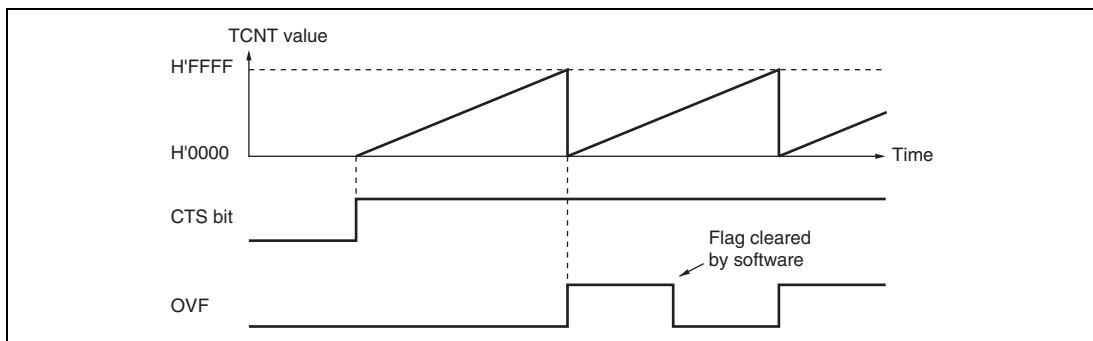
## 11.4 Operation

The timer W has the following operating modes.

- Normal Operation
- PWM Operation

### 11.4.1 Normal Operation

TCNT performs free-running or periodic counting operations. After a reset, TCNT is set as a free-running counter. When the CTS bit in TMRW is set to 1, TCNT starts incrementing the count. When the count overflows from H'FFFF to H'0000, the OVF flag in TSRW is set to 1. If the OVIE in TIERW is set to 1, an interrupt request is generated. Figure 11.2 shows free-running counting.



**Figure 11.2 Free-Running Counter Operation**

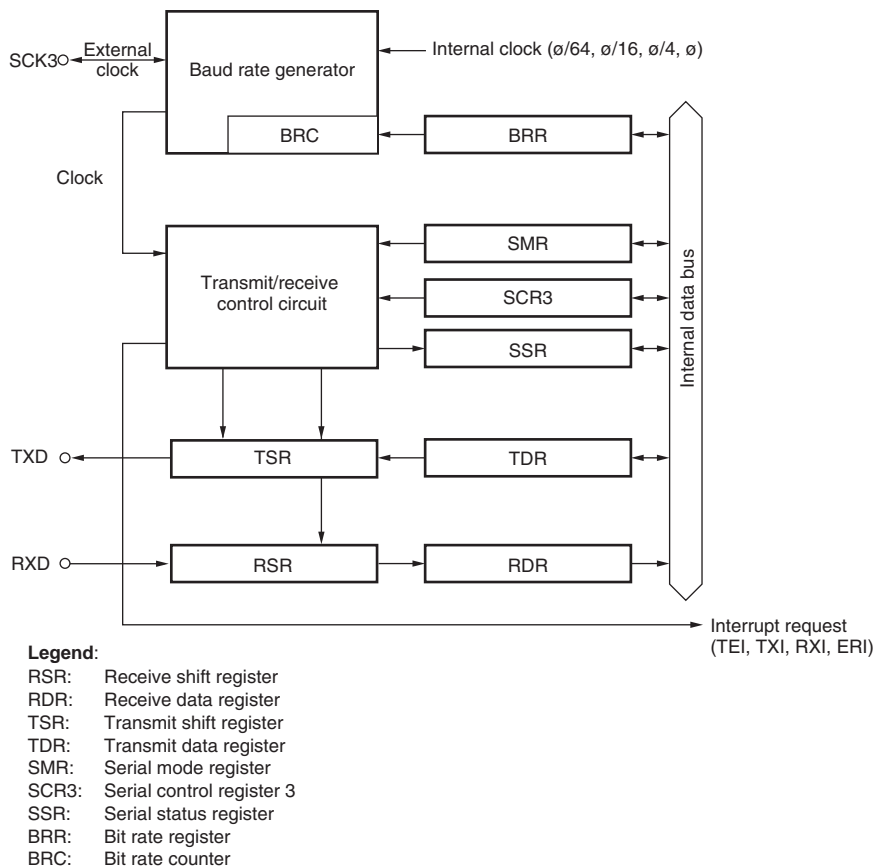


Figure 13.1 Block Diagram of SCI3

**Table 13.5 Examples of BRR Settings for Various Bit Rates (Clocked Synchronous Mode)**  
(2)

Bit Rate (bit/s)	Operating Frequency $\phi$ (MHz)			
	18		20	
	n	N	n	N
110	—	—	—	—
250	—	—	—	—
500	3	140	3	155
1k	3	69	3	77
2.5k	2	112	2	124
5k	1	224	1	249
10k	1	112	1	124
25k	0	179	0	199
50k	0	89	0	99
100k	0	44	0	49
250k	0	17	0	19
500k	0	8	0	9
1M	0	4	0	4
2M	—	—	—	—
2.5M	—	—	0	1
4M	—	—	—	—

**Legend**

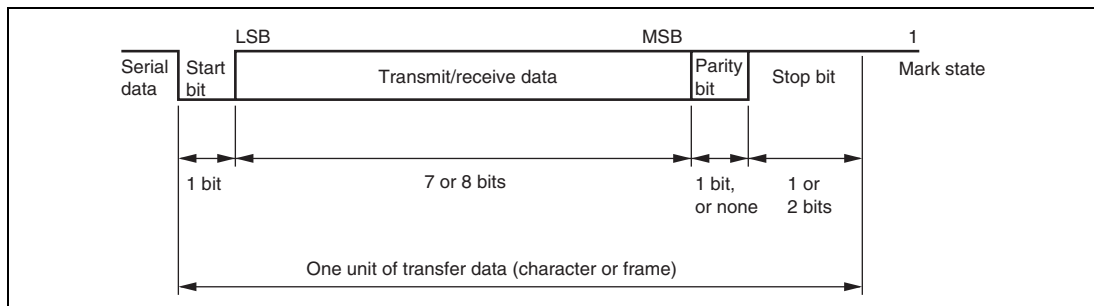
Blank : No setting is available.

— : A setting is available but error occurs.

\* : Continuous transfer is not possible.

## 13.4 Operation in Asynchronous Mode

Figure 13.2 shows the general format for asynchronous serial communication. One character (or frame) consists of a start bit (low level), followed by data (in LSB-first order), a parity bit (high or low level), and finally stop bits (high level). Inside the SCI3, the transmitter and receiver are independent units, enabling full-duplex. Both the transmitter and the receiver also have a double-buffered structure, so data can be read or written during transmission or reception, enabling continuous data transfer.

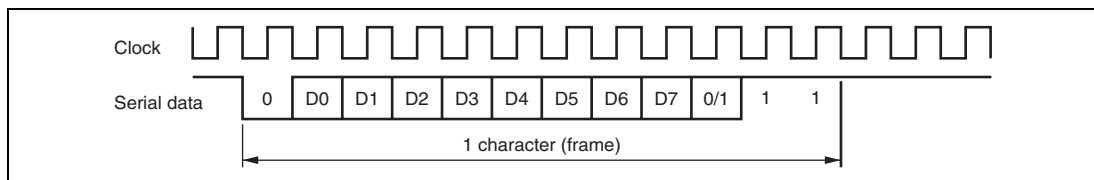


**Figure 13.2 Data Format in Asynchronous Communication**

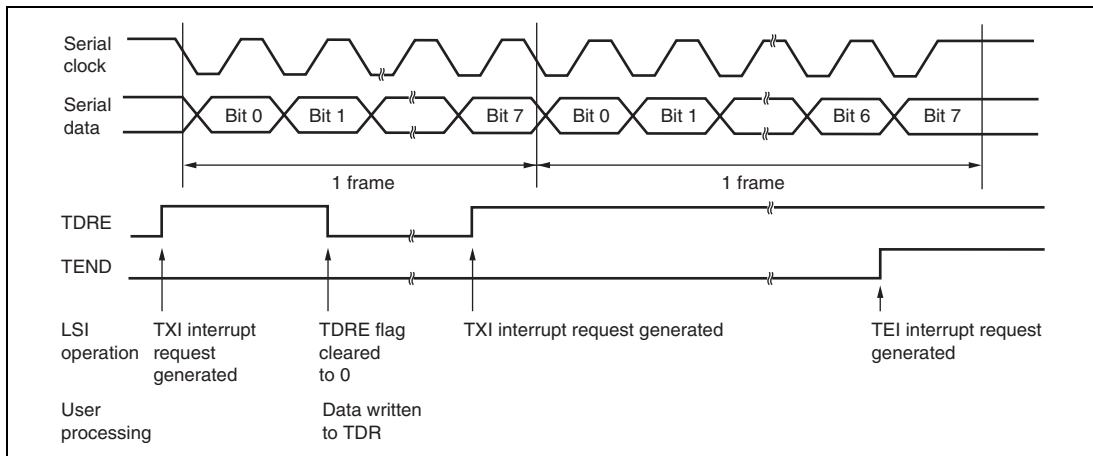
### 13.4.1 Clock

Either an internal clock generated by the on-chip baud rate generator or an external clock input at the SCK3 pin can be selected as the SCI3's serial clock, according to the setting of the COM bit in SMR and the CKE0 and CKE1 bits in SCR3. When an external clock is input at the SCK3 pin, the clock frequency should be 16 times the bit rate used.

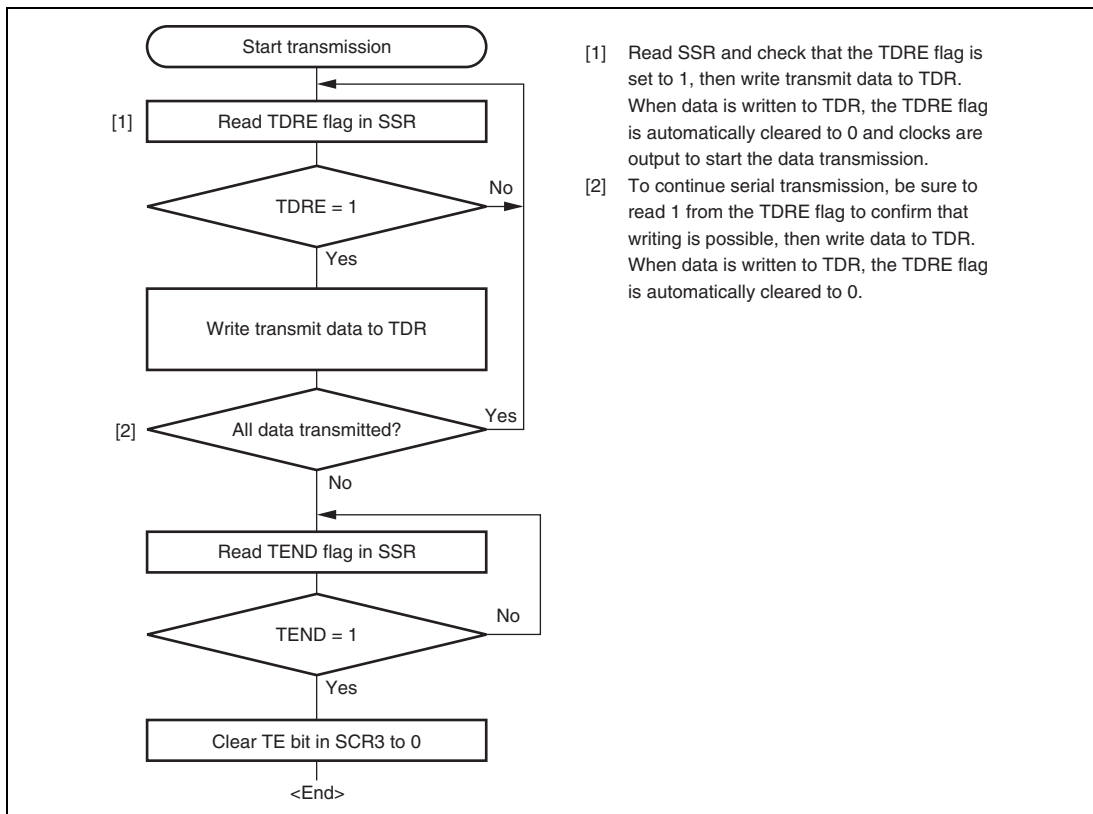
When the SCI3 is operated on an internal clock, the clock can be output from the SCK3 pin. The frequency of the clock output in this case is equal to the bit rate, and the phase is such that the rising edge of the clock is in the middle of the transmit data, as shown in figure 13.3.



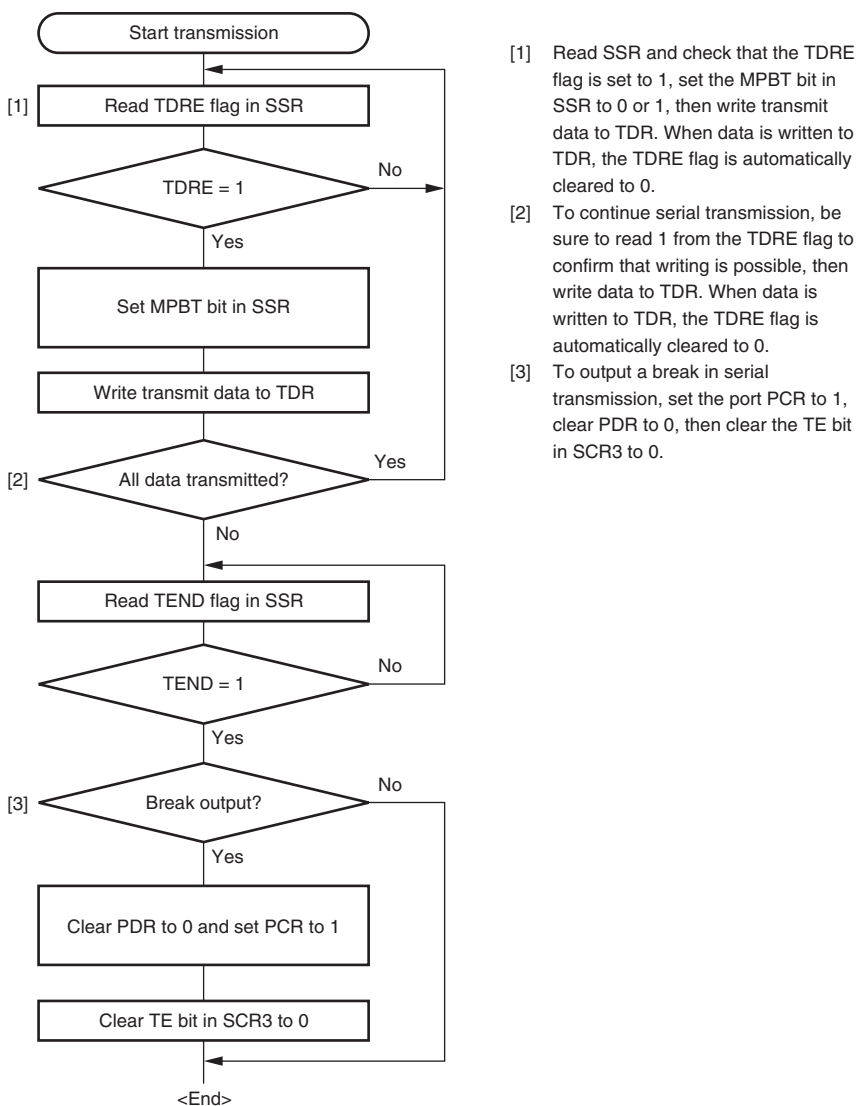
**Figure 13.3 Relationship between Output Clock and Transfer Data Phase (Asynchronous Mode)(Example with 8-Bit Data, Parity, Two Stop Bits)**



**Figure 13.10 Example of SCI3 Transmission in Clocked Synchronous Mode**



**Figure 13.11 Sample Serial Transmission Flowchart (Clocked Synchronous Mode)**



**Figure 13.16 Sample Multiprocessor Serial Transmission Flowchart**

## Section 14 A/D Converter

This LSI includes a successive approximation type 10-bit A/D converter that allows up to four analog input channels to be selected. The block diagram of the A/D converter is shown in figure 14.1.

### 14.1 Features

- 10-bit resolution
- Four input channels
- Conversion time: at least 3.5  $\mu$ s per channel (at 20 MHz operation)
- Two operating modes
  - Single mode: Single-channel A/D conversion
  - Scan mode: Continuous A/D conversion on 1 to 4 channels
- Four data registers
  - Conversion results are held in a 16-bit data register for each channel
- Sample and hold function
- Two conversion start methods
  - Software
  - External trigger signal
- Interrupt request
  - An A/D conversion end interrupt request (ADI) can be generated

**Table 15.1 LVDCR Settings and Select Functions**

LVDCR Settings					Select Functions			
LVDE	LVDSSEL	LVDRE	LVDDE	LVDUE	Power-On Reset	LVDR	Low-Voltage-Detection Falling Interrupt	Low-Voltage-Detection Rising Interrupt
0	*	*	*	*	0	—	—	—
1	1	1	0	0	0	0	—	—
1	0	0	1	0	0	—	0	—
1	0	0	1	1	0	—	0	0
1	0	1	1	1	0	0	0	0

Legend \* means invalid.

### 15.2.2 Low-Voltage-Detection Status Register (LVDSR)

LVDSR indicates whether the power-supply voltage falls below or rises above the respective specified values.

Bit	Bit Name	Initial Value	R/W	Description
7 to 2	—	All 1	—	Reserved These bits are always read as 1, and cannot be modified.
1	LVDDF	0*	R/W	LVD Power-Supply Voltage Fall Flag [Setting condition] When the power-supply voltage falls below Vint (D) (typ. = 3.7 V) [Clearing condition] Writing 0 to this bit after reading it as 1
0	LVDUF	0*	R/W	LVD Power-Supply Voltage Rise Flag [Setting condition] When the power supply voltage falls below Vint (D) while the LVDUE bit in LVDCR is set to 1, then rises above Vint (U) (typ. = 4.0 V) before falling below Vreset1 (typ. = 2.3 V) [Clearing condition] Writing 0 to this bit after reading it as 1

Note: \* Initialized by LVDR.



### 15.3.2 Low-Voltage Detection Circuit

#### (1) LVDR (Reset by Low Voltage Detect) Circuit

Figure 15.3 shows the timing of the LVDR function. The LVDR enters the module-standby state after a power-on reset is canceled. To operate the LVDR, set the LVDE bit in LVDCR to 1, wait for 50  $\mu\text{s}$  ( $t_{\text{LVDRON}}$ ) until the reference voltage and the low-voltage-detection power supply have stabilized by a software timer, etc., then set the LVDRE bit in LVDCR to 1. After that, the output settings of ports must be made. To cancel the low-voltage detection circuit, first the LVDRE bit should be cleared to 0 and then the LVDE bit should be cleared to 0. The LVDE and LVDRE bits must not be cleared to 0 simultaneously because incorrect operation may occur.

When the power-supply voltage falls below the Vreset voltage (typ. = 2.3 V or 3.6 V), the LVDR clears the  $\overline{\text{LVDRES}}$  signal to 0, and resets the prescaler S. The low-voltage detection reset state remains in place until a power-on reset is generated. When the power-supply voltage rises above the Vreset voltage again, the prescaler S starts counting. It counts 131,072 clock ( $\phi$ ) cycles, and then releases the internal reset signal. In this case, the LVDE, LVDSEL, and LVDRE bits in LVDCR are not initialized.

Note that if the power supply voltage ( $V_{\text{CC}}$ ) falls below  $V_{\text{LVDRmin}} = 1.0 \text{ V}$  and then rises from that point, the low-voltage detection reset may not occur.

If the power supply voltage ( $V_{\text{CC}}$ ) falls below  $V_{\text{por}} = 100 \text{ mV}$ , a power-on reset occurs.

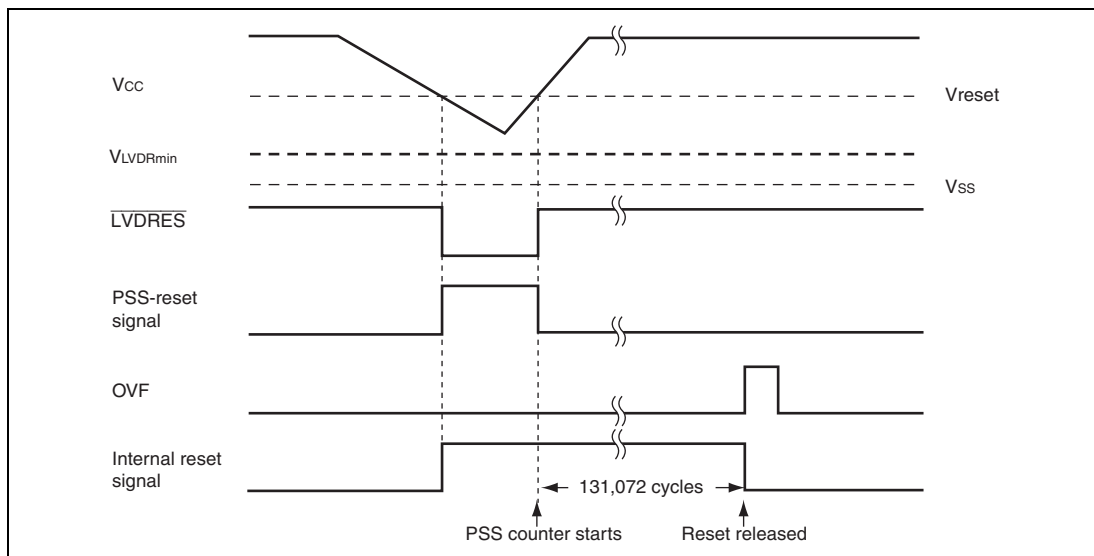


Figure 15.3 Operational Timing of LVDR Circuit

**Table 18.2 DC Characteristics (2)**

$V_{CC} = 3.0\text{ V to }5.5\text{ V}$ ,  $V_{SS} = 0.0\text{ V}$ ,  $T_a = -20^{\circ}\text{C to }+75^{\circ}\text{C}$ , unless otherwise indicated.

Item	Symbol	Applicable Pins	Test Condition	Values			Unit
				Min	Typ	Max	
Allowable output low current (per pin)	$I_{OL}$	Output pins except port 8	$V_{CC} = 4.0\text{ V to }5.5\text{ V}$	—	—	2.0	mA
		Port 8		—	—	20.0	mA
		Port 8		—	—	10.0	mA
		Output pins except port 8		—	—	0.5	mA
Allowable output low current (total)	$\Sigma I_{OL}$	Output pins except port 8	$V_{CC} = 4.0\text{ V to }5.5\text{ V}$	—	—	40.0	mA
		Port 8		—	—	80.0	mA
		Output pins except port 8		—	—	20.0	mA
		Port 8		—	—	40.0	mA
Allowable output high current (per pin)	$I_{OH}$	All output pins	$V_{CC} = 4.0\text{ V to }5.5\text{ V}$	—	—	2.0	mA
				—	—	0.2	mA
Allowable output high current (total)	$I_{OH}$	All output pins	$V_{CC} = 4.0\text{ V to }5.5\text{ V}$	—	—	30.0	mA
				—	—	8.0	mA

### A.3 Number of Execution States

The status of execution for each instruction of the H8/300H CPU and the method of calculating the number of states required for instruction execution are shown below. Table A.4 shows the number of cycles of each type occurring in each instruction, such as instruction fetch and data read/write. Table A.3 shows the number of states required for each cycle. The total number of states required for execution of an instruction can be calculated by the following expression:

$$\text{Execution states} = I \times S_I + J \times S_J + K \times S_K + L \times S_L + M \times S_M + N \times S_N$$

**Examples:** When instruction is fetched from on-chip ROM, and an on-chip RAM is accessed.

BSET #0, @FF00

From table A.4:

$$I = L = 2, \quad J = K = M = N = 0$$

From table A.3:

$$S_I = 2, \quad S_L = 2$$

$$\text{Number of states required for execution} = 2 \times 2 + 2 \times 2 = 8$$

When instruction is fetched from on-chip ROM, branch address is read from on-chip ROM, and on-chip RAM is used for stack area.

JSR @@ 30

From table A.4:

$$I = 2, \quad J = K = 1, \quad L = M = N = 0$$

From table A.3:

$$S_I = S_J = S_K = 2$$

$$\text{Number of states required for execution} = 2 \times 2 + 1 \times 2 + 1 \times 2 = 8$$

## Appendix D Package Dimensions

The package dimensions that are shown in the Renesas Semiconductor Packages Data Book have priority.

